

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	((method process) with (second with (chip die (semiconductor near1 (device element component)))) with stack\$3 with ((volume amount) near2 adhesive) with predetermine\$3 with (permanent near1 (distance space\$2)) with ((without no) near3 force)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:04
L2	0	((method process) same (second with (chip die (semiconductor near1 (device element component)))) same stack\$3 same ((volume amount) near2 adhesive) same predetermine\$3 same (permanent near1 (distance space\$2)) same ((without no) near3 force)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:06
L3	0	((method process) same (second with (chip die (semiconductor near1 (device element component)))) same ((volume amount) near2 adhesive) same predetermine\$3 same (permanent near1 (distance space\$2)) same ((without no) near3 force)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:10
L4	0	((method process) same (second with (chip die (semiconductor near1 (device element component)))) same ((volume amount) near2 adhesive) same predetermine\$3 same (permanent near1 (distance space\$2)) same ((without no) near3 (press\$3 push\$3 force))).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:07
L5	0	((method process) and (second with (chip die (semiconductor near1 (device element component)))) and ((volume amount) near2 adhesive) and predetermine\$3 and (permanent near1 (distance space\$2)) and ((without no) near3 (press\$3 push\$3 force))).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:09
L6	0	((method process) with (second with (chip die (semiconductor near1 (device element component)))) with ((volume amount) near2 adhesive) with predetermine\$3 with (permanent near1 (distance space\$2)) with (press\$3 push\$3 force)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:10

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L7	0	((method process) same (second with (chip die (semiconductor near1 (device element component)))) same ((volume amount) near2 adhesive) same predetermine\$3 same (permanent near1 (distance space\$2)) same (press\$3 push\$3 force)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:11
L8	0	((method process) and (second with (chip die (semiconductor near1 (device element component)))) and ((volume amount) near2 adhesive) and predetermine\$3 and (permanent near1 (distance space\$2)) and (press\$3 push\$3 force)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:12
L9	0	((method process) and (second with (chip die (semiconductor near1 (device element component)))) and ((volume amount) near2 adhesive) and predetermine\$3 and (permanent near1 (distance space\$2)) and (press\$3 push\$3 forc\$3)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:21
L10	5301	438/109,107,118,455.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/09/07 09:17
L11	8003	257/686,777,782,783,784,e27.137, e27.144,e27.161.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/09/07 09:20
L12	12505	10 11	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2007/09/07 09:20
L13	0	12 and (second near2 (chip die (semiconductor near1 (device element component)))) and ((volume amount) near2 adhesive) and (permanent near1 (distance space\$2)) and (press\$3 push\$3 forc\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:24
L14	128	12 and (second near2 (chip die (semiconductor near1 (device element component)))) and ((volume amount) near2 adhesive) and (distance space\$2) and (press\$3 push\$3 forc\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:29
L15	12	((second near2 (chip die (semiconductor near1 (device element component)))) and ((volume amount) near2 adhesive) and (distance space\$2) and (press\$3 push\$3 forc\$3)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:25

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L16	128	14 and (method process)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:29
L17	119	16 and (wire wiring)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/07 09:29